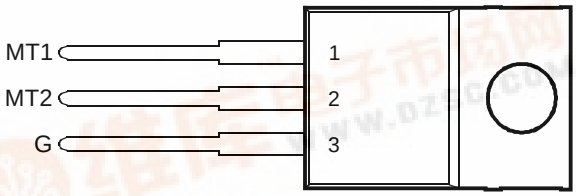
TIC225 SERIES
SILICON TRIACS

JULY 1975 - REVISED MARCH 1997

- **Sensitive Gate Triacs**
- **8 A RMS, 70 A Peak**
- **Glass Passivated Wafer**
- **400 V to 800 V Off-State Voltage**
- **Max I_{GT} of 5 mA (Quadrant 1)**

TO-220 PACKAGE
(TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDC2ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Repetitive peak off-state voltage (see Note 1)	TIC225D TIC225M TIC225S TIC225N	V_{DRM}	400 600 700 800	V
Full-cycle RMS on-state current at (or below) 70°C case temperature (see Note 2)		$I_{T(RMS)}$	8	A
Peak on-state surge current full-sine-wave (see Note 3)		I_{TSM}	70	A
Peak on-state surge current half-sine-wave (see Note 4)		I_{TSM}	80	A
Peak gate current		I_{GM}	±1	A
Peak gate power dissipation at (or below) 85°C case temperature (pulse width ≤ 200 µs)		P_{GM}	2.2	W
Average gate power dissipation at (or below) 85°C case temperature (see Note 5)		$P_{G(AV)}$	0.9	W
Operating case temperature range		T_C	-40 to +110	°C
Storage temperature range		T_{stg}	-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds		T_L	230	°C

NOTES: 1. These values apply bidirectionally for any value of resistance between the gate and Main Terminal 1.
2. This value applies for 50-Hz full-sine-wave operation with resistive load. Above 70°C derate linearly to 110°C case temperature at the rate of 200 mA/°C.
3. This value applies for one 50-Hz full-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.
4. This value applies for one 50-Hz half-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.
5. This value applies for a maximum averaging time of 20 ms.

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
I_{DRM}	Repetitive peak off-state current	V_D = rated V_{DRM}	I_G = 0	T_C = 110°C			±2	mA
I_{GTM}	Peak gate trigger current	V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		0.8	5	mA
		V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-4.5	-20	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-3.5	-10	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		11.7	30	
V_{GTM}	Peak gate trigger voltage	V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		0.7	2	V
		V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-0.7	-2	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-0.8	-2	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		0.9	2	

† All voltages are with respect to Main Terminal 1.

electrical characteristics at 25°C case temperature (unless otherwise noted) (continued)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V_{TM}	Peak on-state voltage	I_{TM} = ±12 A	I_G = 50 mA	(see Note 6)		±1.6	±2.1	V
I_H	Holding current	V_{supply} = +12 V†	I_G = 0	Init' I_{TM} = 100 mA		3	20	mA
		V_{supply} = -12 V†	I_G = 0	Init' I_{TM} = -100 mA		-4.7	-20	
I_L	Latching current	V_{supply} = +12 V†	(see Note 7)				30	mA
		V_{supply} = -12 V†					-30	
dv/dt	Critical rate of rise of off-state voltage	V_{DRM} = Rated V_{DRM}	I_G = 0	T_C = 110°C		±50		V/µs
$dv/dt_{(c)}$	Critical rise of commutation voltage	V_{DRM} = Rated V_{DRM}	I_{TRM} = ±12 A	T_C = 70°C	±1	±1.5	±4.5	V/µs

† All voltages are with respect to Main Terminal 1.

NOTES: 6. This parameter must be measured using pulse techniques, t_p = ≤ 1 ms, duty cycle ≤ 2 %. Voltage-sensing contacts separate from the current carrying contacts are located within 3.2 mm from the device body.

7. The triacs are triggered by a 15-V (open-circuit amplitude) pulse supplied by a generator with the following characteristics: R_G = 100 Ω, $t_{p(g)}$ = 20 µs, t_r = ≤ 15 ns, f = 1 kHz

thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			2.5	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

TYPICAL CHARACTERISTICS

GATE TRIGGER CURRENT
vs
CASE TEMPERATURE

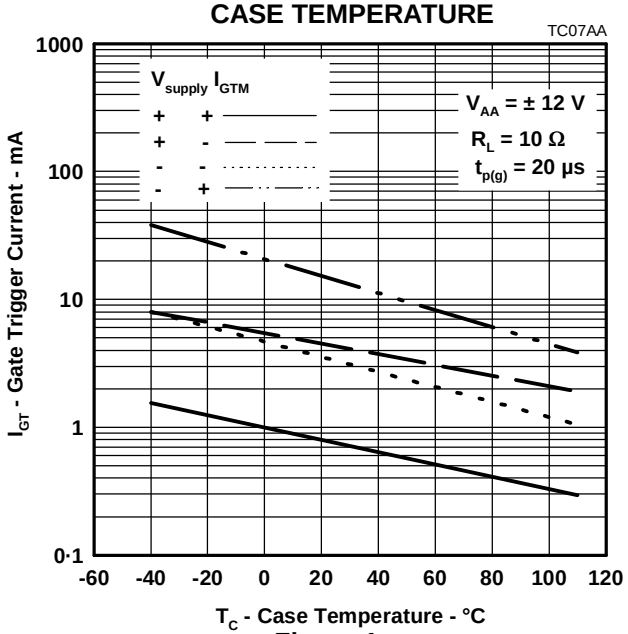


Figure 1.

GATE TRIGGER VOLTAGE
vs
CASE TEMPERATURE

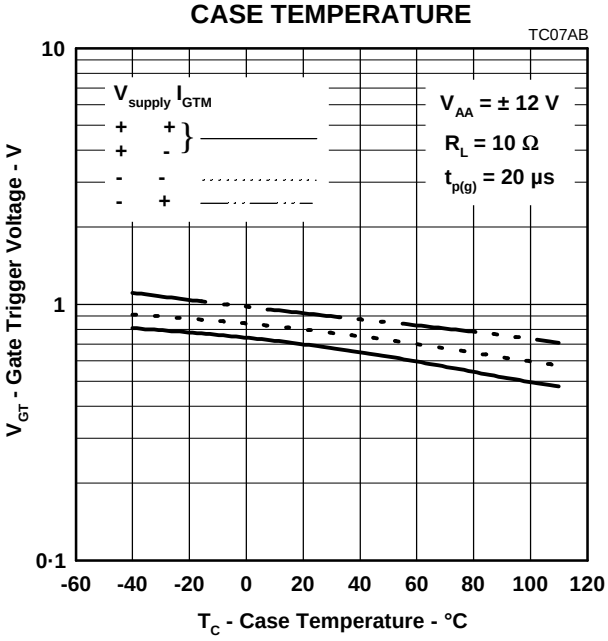


Figure 2.

TYPICAL CHARACTERISTICS

HOLDING CURRENT
vs
CASE TEMPERATURE

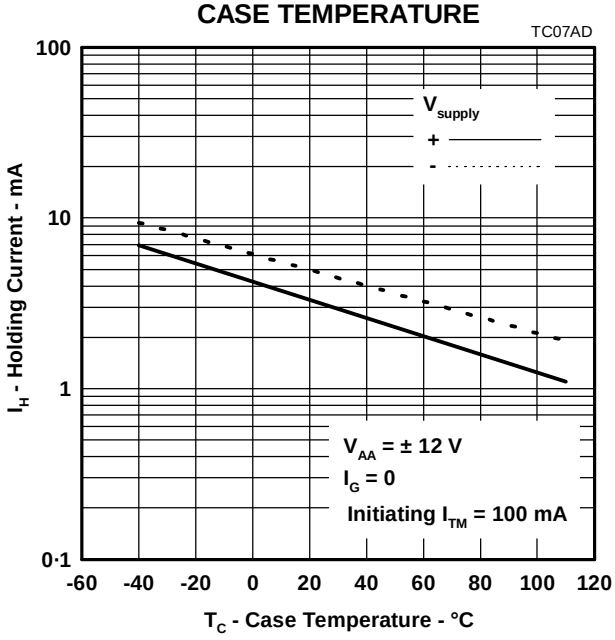


Figure 3.

GATE FORWARD VOLTAGE
vs
GATE FORWARD CURRENT

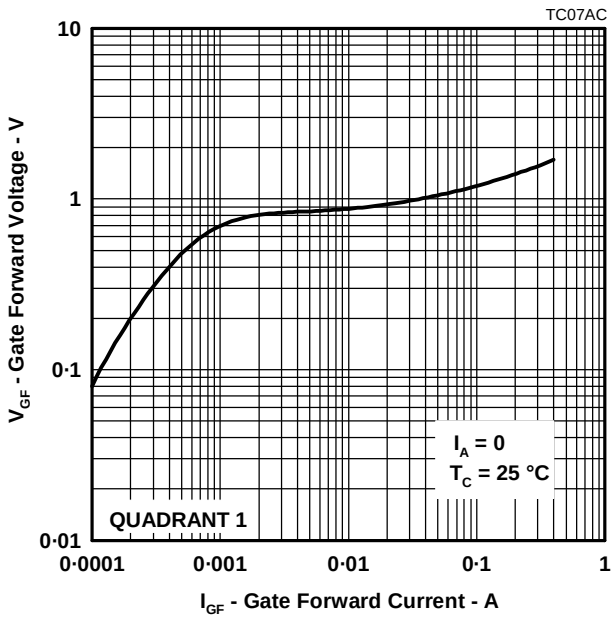


Figure 4.

LATCHING CURRENT
vs
CASE TEMPERATURE

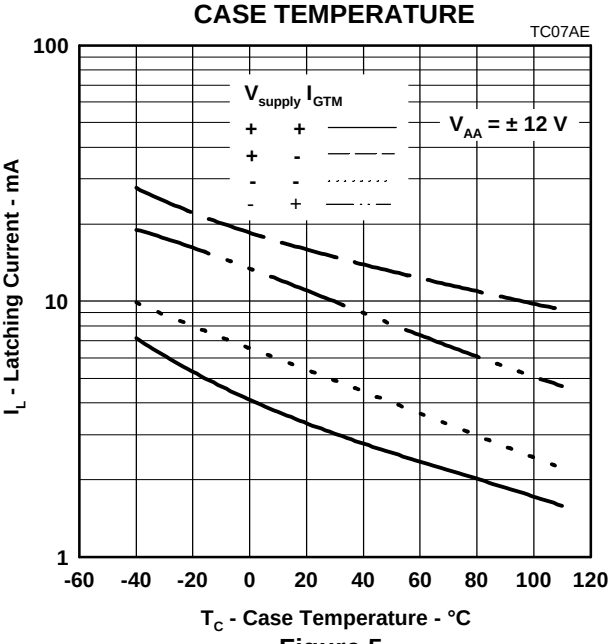


Figure 5.

SURGE ON-STATE CURRENT
vs
CYCLES OF CURRENT DURATION

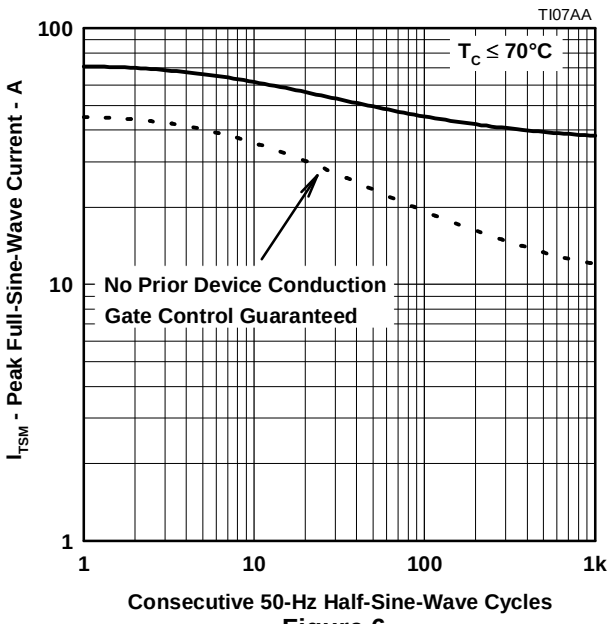


Figure 6.

TYPICAL CHARACTERISTICS

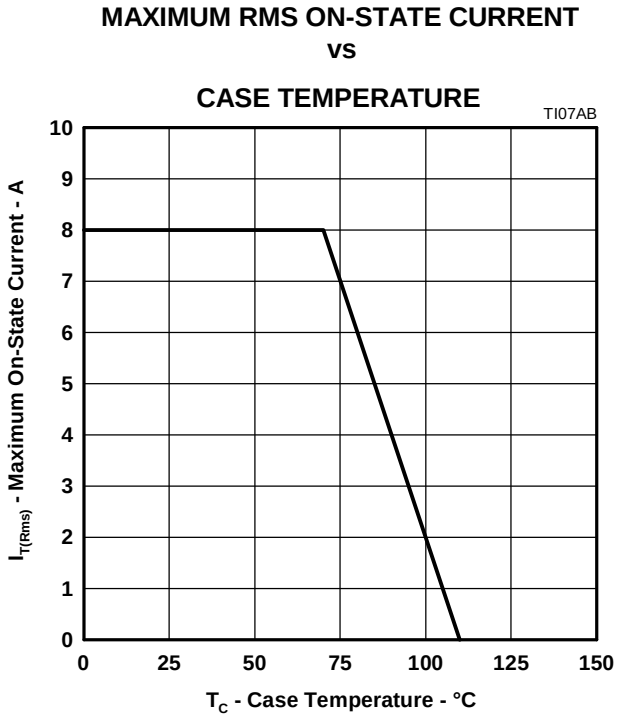
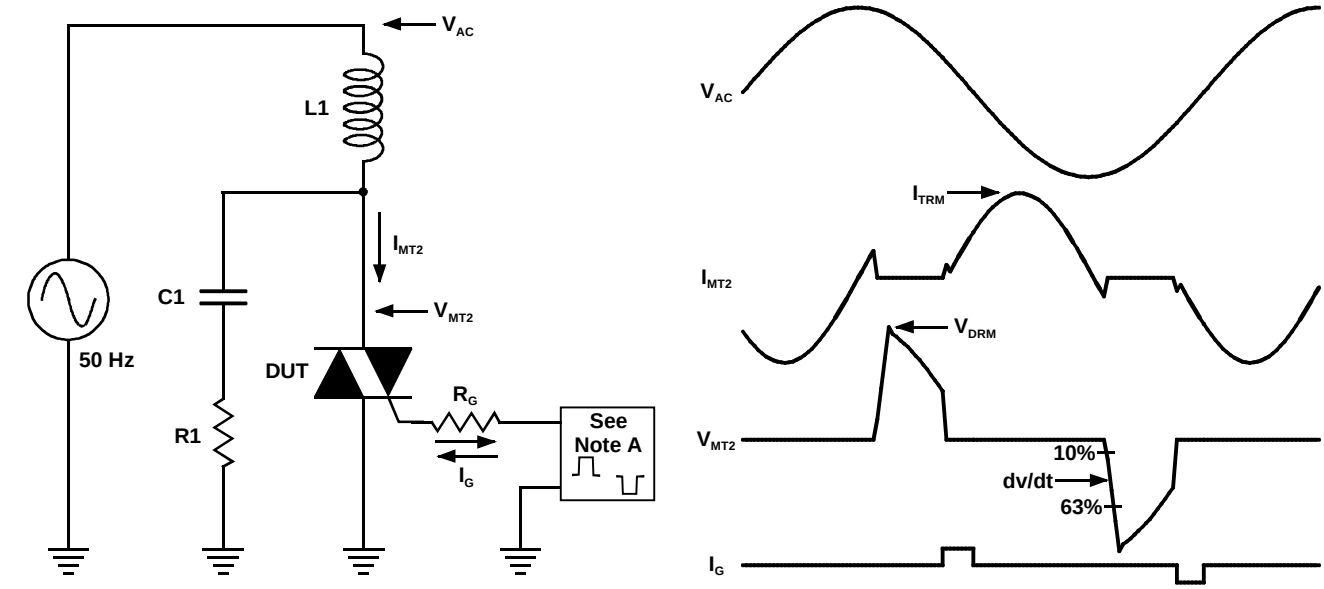


Figure 7.

PARAMETER MEASUREMENT INFORMATION



NOTE A: The gate-current pulse is furnished by a trigger circuit which presents essentially an open circuit between pulses. The pulse is timed so that the off-state-voltage duration is approximately 800 µs.

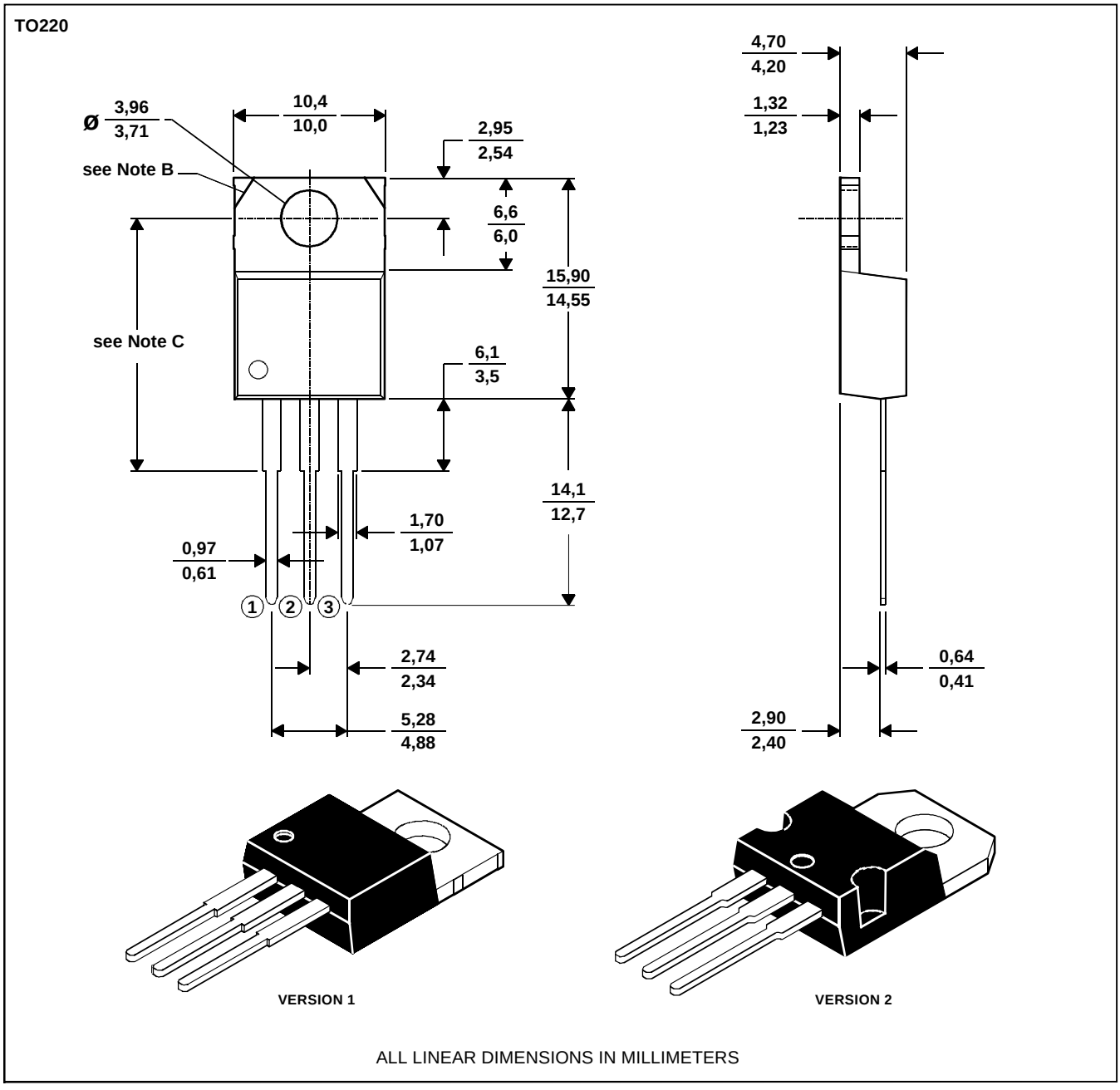
PMC2AA

Figure 8.

MECHANICAL DATA

TO-220
3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.
B. Mounting tab corner profile according to package version.
C. Typical fixing hole centre stand off height according to package version.
Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE

TIC225 SERIES
SILICON TRIACS

JULY 1975 - REVISED MARCH 1997

IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.